

AL 501 Aluminum Nitride Powder

Catalog #		
Formula	AIN	
Purity	99.9%	
Particle size	7–10-micron APS	

Chemistry			
Elements	Specification	Typical Results	
Iron	0.05 max	0.02	
Silicon	0.05 max	0.007	

7–10-micron APS				
		D50	D97	
Microns		7 – 10-micron aps	20-micron max	
Surface Area, m2/gm		2.3 -	- 3.5	

Properties				
Thermal Conductivity (sintered)	70-180 W/mK*			
Dielectric Constant	8.2-9.0			
Color	Gray			
Density	3.26 g/cm3			
Sublimes @	2450 degrees C			
Crystal Structure	hexagonal			

- <u>Chemical</u>: Exhibits good resistance to several corrosive materials and does not react with most metals such as Al, Cu, Li, U, ferrous and some super alloys. It is also resistant to many molten salts including carbonates, chlorides and cryolite.
- <u>Thermal</u>: 8 to 10 times more thermally conductive than alumina, and its conductivity will not deteriorate with rising temperatures. With a relatively low thermal expansion coefficient, AIN structures meet thermo-mechanical requirements for many electronic device components.
- **Electrical**: High dielectric strength and low loss tangent makes it high performance insulator for many semi-conductor and power electronic applications.

